BBD-130-T-B BHS-125-G-A BBS-116-G-C BBS, BBL, BHS, BBD, BDL SERIES

NO. PINS

PER ROW

BDL-110-G-F

PLATING

OPTION

STYLE

(2.54 mm) .100"

CHINED BOARD STACKING STRIPS

(2.54) .100 x No. of Positions

BBL

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BDL

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BBS

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(2.54) .100 TYF

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←(2.54) .100 TYF

(2.54) .100 x No. of Positions

TYPE

STRIP

BBS

= Standard Single Row

 BBL

= Low-Profile Single Row

BHS

= High Temp Single Row

BBD

= Standard Double Row

BDL

= Low-Profile Double Row

BBL-112-T-E

Mates with:

SS, SD, HSS, SL, SDL, ESS. ESD

FEATURES

- Low-profile design achieves (3.89 mm) .153" board spacings when mated with SL Series.
- · Approach the reliability of a permanent connection with the flexibility of a separable connection.

SPECIFICATIONS

For complete specifications see www.samtec.com?BBS, www.samtec.com?BBL, www.samtec.com?BHS www.samtec.com?BBD or www.samtec.com?BDL

Insulator Material: Black Liquid Crystal Polymer (BBL, BHS) Black Glass Filled Polyester (BBS, BBD, BDL) Temperature Range: -55 °C to +125 °C Terminal Material: Phosphor Bronze or Brass Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Lead-Free Solderable:
Yes (BBL, BDL, BHS-S)

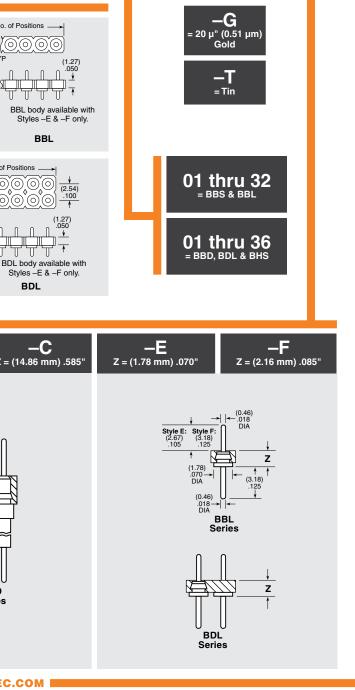
No, Lead Wave only (BBS, BBD, BHS-N)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



–B _Δ Z = (5.33 mm) .210" Z = (8.51 mm) .335" Z = (14.86 mm) .585" (3.18) (1.27) .050 Z (1.78).070 DIA (3.18) RRD Series **BBS and BHS**



Note:

Some lengths, styles and options are non-standard, non-returnable.